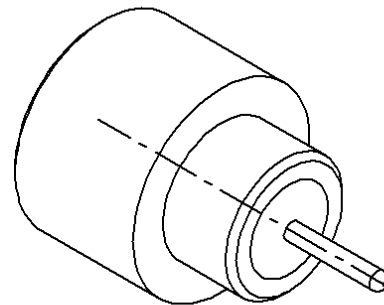
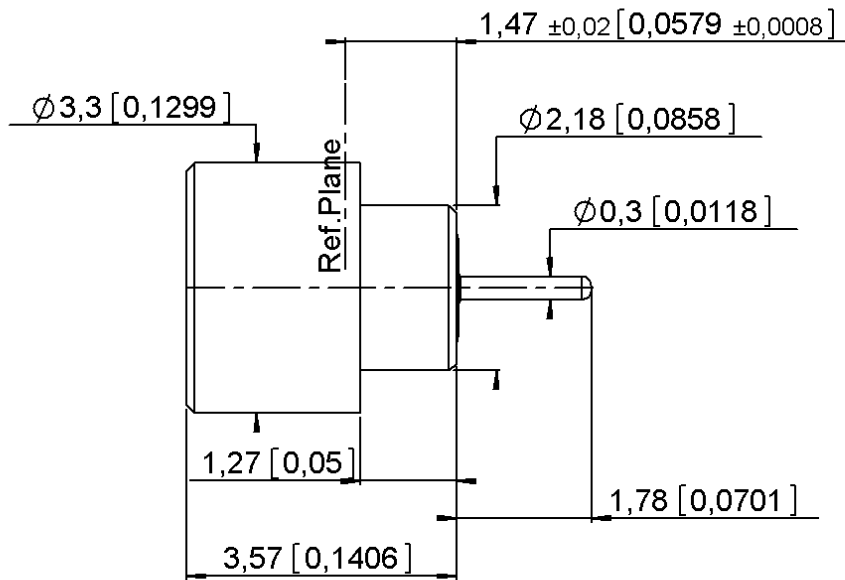



HERMETIC STRAIGHT MALE RECEPTACLE
SOLDER TYPE - SMOOTH BORE

R201.645.700

Series : **SMPM**

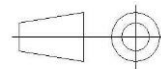


 Scale : 1/1

All dimensions are in mm.

pn

ao



COMPONENTS	MATERIALS	PLATING (µm)
BODY	DILVER P1	GOLD 0.5 OVER NICKEL 2
CENTER CONTACT	DILVER P1	GOLD 0.5 OVER NICKEL 2
OUTER CONTACT	-	-
INSULATOR	GLASS	-
GASKET	-	-
OTHERS PARTS	-	-
-	-	-
-	-	-

Issue : 04-02-16B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



HERMETIC STRAIGHT MALE RECEPTACLE

R201.645.700

SOLDER TYPE - SMOOTH BORE

Series : **SMPM**

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance	50	Ω
Frequency	0-40	GHz
VSWR	*1.35 + 0,0000	x F(GHz) Maxi
Insertion loss	0.12	$\sqrt{F}(\text{GHz})$ dB Maxi
RF leakage	- (NA	- F(GHz)) dB Maxi
Voltage rating	335	Veff Maxi
Dielectric withstanding voltage	500	Veff mini
Insulation resistance	5000	M Ω mini

Operating temperature	-65/+165	$^{\circ}\text{C}$
Hermetic seal	10-8	Atm.cm ³ /s
Panel leakage	NA	

OTHER CHARACTERISTICS

Assembly instruction

Others :
*1.15 at 18 GHz

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	6.7	N mini
Axial force – Opposite end	6.7	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	500	Cycles mini
Weight	0,2000	g

Issue : 04-02-16B

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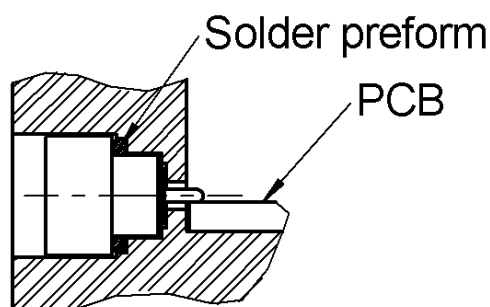


HERMETIC STRAIGHT MALE RECEPTACLE

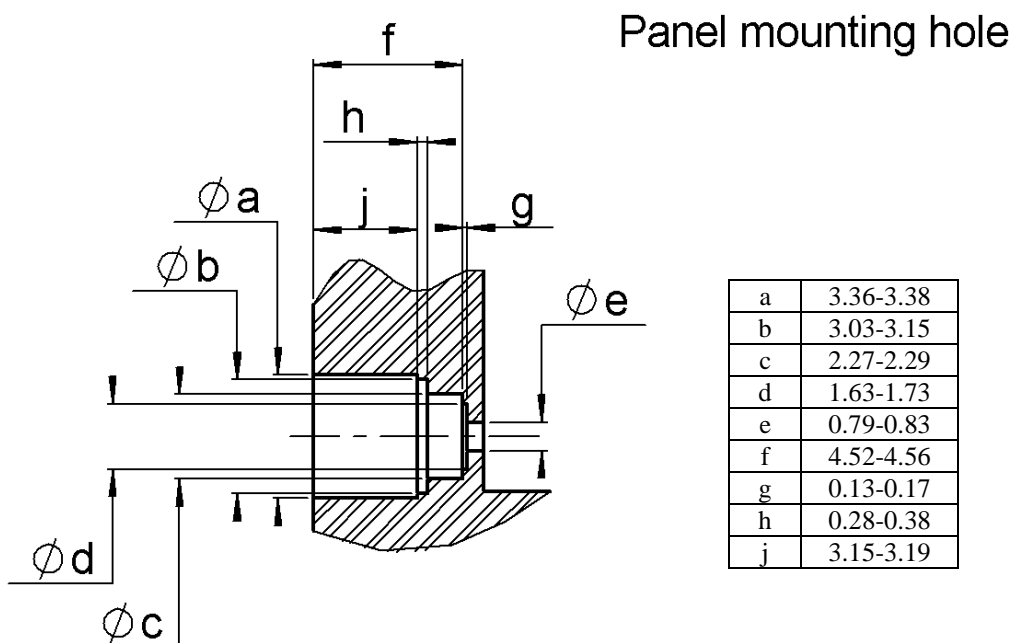
R201.645.700

SOLDER TYPE - SMOOTH BORE

Series : **SMPM**



1. Degrease and clean connector and box
2. Solder the connector on the panel
we advise SnAg4 Cu0.5, we recommend a low residue flux. Preheating at 100 °C. Take care not to exceed 260°C during solder operation
3. Solder the pin on the track
we advise SnAg4 Cu0.5, we recommend a low residue flux. Preheating at 100 °C (only for ceramic substrate). Take care not to exceed 260°C during solder operation



Issue : 04-02-16B

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